

(19)



JAPANESE PATENT OFFICE

PATENT ABSTRACTS OF JAPAN

(11) Publication number: 09096822 A
(43) Date of publication of application: 08.04.1997

(51) Int. Cl. G02F 1/1339

(21) Application number: 07254085
(22) Date of filing: 29.09.1995

(71) Applicant: TOSHIBA CORP
(72) Inventor: CHOKAI MASAKI
YAMAGATA ICHI

(54) SUBSTRATE JOINING DEVICE

(57) Abstract:

PROBLEM TO BE SOLVED: To provide a substrate joining device capable of preventing mispositioning and improving substrate efficiency and production efficiency at the time of joining two sheets of substrates.

ond substrate A closer until the spacing is regulated by spacers, thereby adjusting the spacing to the prescribed spacing and a sealant curing means 130 for joining the first substrate F and the second substrate A by maintaining the spacing adjusted by this spacing adjusting means 97 and curing the sealant S in the state of maintaining the prescribed spacing.

COPYRIGHT: (C)1997,JPO

SOLUTION: The substrate joining device for joining the first substrate F and the second substrate A by superposing these substrates on each other via a sealant S in the state of maintaining a prescribed spacing there-between by spacers has a positioning means 76 which relatively positions the first substrate F and the second substrate A, a spacing adjusting means 97 for pressurizing the first substrate F and the second substrate A in a positioned state under prescribed load to bring the spacing between the first substrate F and the sec-

